## 2SD2549

## Silicon NPN triple diffusion planar type

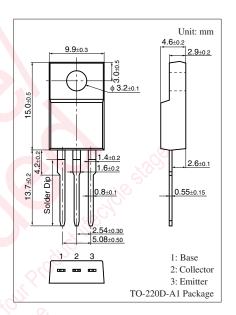
### For power amplification

#### ■ Features

- High forward current transfer ratio h<sub>FE</sub> which has satisfactory linearity
- $\bullet$  Low collector-emitter saturation voltage  $V_{\text{CE}(\text{sat})}$
- Full-pack package which can be installed to the heat sink with one screw

### ■ Absolute Maximum Ratings $T_C = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	80	V	
Collector-emitter voltage (Base open)	$V_{CEO}$	80	V	
Emitter-base voltage (Collector open)	$V_{EBO}$	6	V	
Collector current	$I_{C}$	3	A	
Peak collector current	$I_{CP}$	5	A	
Collector power	P <sub>C</sub>	20	W	
dissipation $T_a = 25^{\circ}C$		2.0	1,05	
Junction temperature	$T_{j}$	150	°C	
Storage temperature	$T_{stg}$	-55 to +150	S °C	



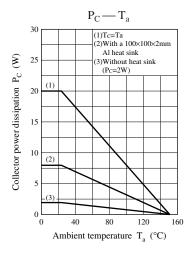
## ■ Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

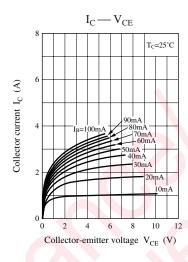
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 30 \text{ mA}, I_B = 0$	80	0		V
Base-emitter voltage	$V_{BE}$	$V_{CE} = 4 \text{ V}, I_{C} = 3 \text{ A}$	750		1.8	V
Collector-emitter cutoff current (E-B short)	I <sub>CES</sub>	$V_{CE} = 70 \text{ V}, V_{BE} = 0$			100	μΑ
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = 70 \text{ V}, I_{B} = 0$			100	μΑ
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = 6 \text{ V}, I_C = 0$			1	mA
Forward current transfer ratio	h <sub>FE1</sub> *	$V_{CE} = 4 \text{ V}, I_{C} = 1 \text{ A}$	70		250	_
	h <sub>FE2</sub>	$V_{CE} = 4 \text{ V}, I_{C} = 3 \text{ A}$	10			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 3 \text{ A}, I_B = 0.375 \text{ A}$			0.7	V
Transition frequency	$f_T$	$V_{CE} = 10 \text{ V}, I_{C} = 0.5 \text{ A}, f = 10 \text{ MHz}$		30		MHz
Turn-on time	t <sub>on</sub>	$I_C = 1 \text{ A}, I_{B1} = 0.1 \text{ A}, I_{B2} = -0.1 \text{ A}$			0.5	μs
Storage time	t <sub>stg</sub>	$V_{CC} = 50 \text{ V}$			4.5	μs
Fall time	t <sub>f</sub>				0.5	μs

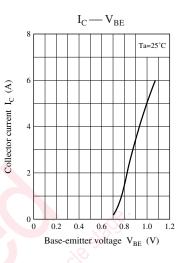
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

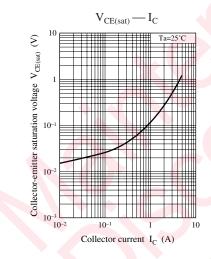
#### 2. \*: Rank classification

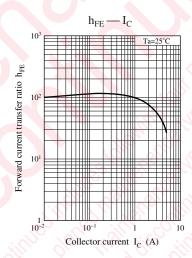
Rank	Q	Р
$h_{\mathrm{FE1}}$	70 to 150	120 to 250

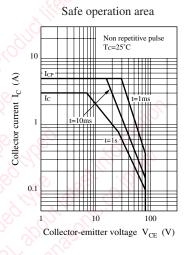


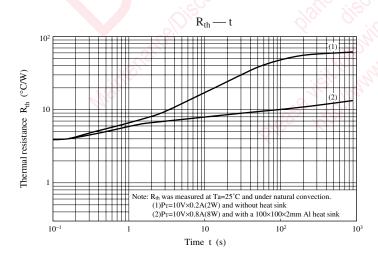












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